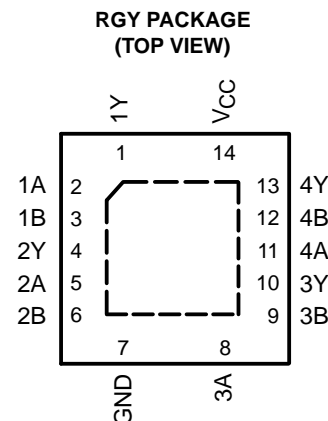


## FEATURES

- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max  $t_{pd}$  of 2.2 ns at 1.8 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 8$ -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



## DESCRIPTION/ORDERING INFORMATION

This quadruple 2-input positive-NOR gate is operational at 0.8-V to 2.7-V  $V_{CC}$ , but is designed specifically for 1.65-V to 1.95-V  $V_{CC}$  operation.

The SN74AUC02 device performs the Boolean function  $Y = \overline{A + B}$  or  $Y = \overline{A} \cdot \overline{B}$  in positive logic.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AUC02RGYR	MS02

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (EACH GATE)

INPUTS		OUTPUT Y
A	B	
H	X	L
X	H	L
L	L	H

## LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN74AUC02

## QUADRUPLE 2-INPUT POSITIVE-NOR GATE

SCES511A–NOVEMBER 2003–REVISED MARCH 2005



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	3.6	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	3.6	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	3.6	V
$V_O$	Output voltage range <sup>(2)</sup>	–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	–50	mA
$I_{OK}$	Output clamp current	$V_O < 0$	–50	mA
$I_O$	Continuous output current		±20	mA
	Continuous current through $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>		47	°C/W
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-5.

### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	0.8	2.7	V
$V_{IH}$	High-level input voltage	$V_{CC} = 0.8$ V	$V_{CC}$	V
		$V_{CC} = 1.1$ V to 1.95 V	$0.65 \times V_{CC}$	
		$V_{CC} = 2.3$ V to 2.7 V	1.7	
$V_{IL}$	Low-level input voltage	$V_{CC} = 0.8$ V	0	V
		$V_{CC} = 1.1$ V to 1.95 V	$0.35 \times V_{CC}$	
		$V_{CC} = 2.3$ V to 2.7 V	0.7	
$V_I$	Input voltage	0	3.6	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 0.8$ V	–0.7	mA
		$V_{CC} = 1.1$ V	–3	
		$V_{CC} = 1.4$ V	–5	
		$V_{CC} = 1.65$ V	–8	
		$V_{CC} = 2.3$ V	–9	
$I_{OL}$	Low-level output current	$V_{CC} = 0.8$ V	0.7	mA
		$V_{CC} = 1.1$ V	3	
		$V_{CC} = 1.4$ V	5	
		$V_{CC} = 1.65$ V	8	
		$V_{CC} = 2.3$ V	9	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 0.8$ V to 1.65 V <sup>(2)</sup>	20	ns/V
		$V_{CC} = 1.65$ V to 1.95 V <sup>(3)</sup>	10	
		$V_{CC} = 2.3$ V to 2.7 V <sup>(3)</sup>	5	
$T_A$	Operating free-air temperature	–40	85	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (2) The data was taken at  $C_L = 15$  pF,  $R_L = 2$  k $\Omega$  (see Figure 1).
- (3) The data was taken at  $C_L = 30$  pF,  $R_L = 500$   $\Omega$  (see Figure 1).

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = –100 µA	0.8 V to 2.7 V	V <sub>CC</sub> – 0.1			V
		I <sub>OH</sub> = –0.7 mA	0.8 V	0.55			
		I <sub>OH</sub> = –3 mA	1.1 V	0.8			
		I <sub>OH</sub> = –5 mA	1.4 V	1			
		I <sub>OH</sub> = –8 mA	1.65 V	1.2			
		I <sub>OH</sub> = –9 mA	2.3 V	1.8			
V <sub>OL</sub>		I <sub>OL</sub> = 100 µA	0.8 V to 2.7 V	0.2			V
		I <sub>OL</sub> = 0.7 mA	0.8 V	0.25			
		I <sub>OL</sub> = 3 mA	1.1 V	0.3			
		I <sub>OL</sub> = 5 mA	1.4 V	0.4			
		I <sub>OL</sub> = 8 mA	1.65 V	0.45			
		I <sub>OL</sub> = 9 mA	2.3 V	0.6			
I <sub>I</sub>	A or B inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	0 to 2.7 V	±5			µA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 2.7 V	0	±10			µA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	0.8 V to 2.7 V	10			µA
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	2.5 V	2			pF

(1) All typical values are at T<sub>A</sub> = 25°C.

## Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V ± 0.1 V		V <sub>CC</sub> = 1.5 V ± 0.1 V		V <sub>CC</sub> = 1.8 V ± 0.15 V			V <sub>CC</sub> = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	4.6	0.8	3.4	0.7	2.4	0.6	0.9	2.2	0.5	1.3	ns

## Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V			V <sub>CC</sub> = 2.5 V ± 0.2 V		UNIT
			MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	0.8	1.5	2.4	0.6	2	ns

## Operating Characteristics

T<sub>A</sub> = 25°C

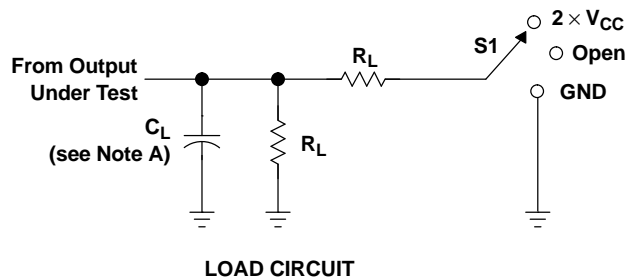
PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> = 1.5 V	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	UNIT
		TYP	TYP	TYP	TYP	TYP	
C <sub>pd</sub> Power dissipation capacitance	f = 10 MHz	13	13	13	13	16	pF

# SN74AUC02

## QUADRUPLE 2-INPUT POSITIVE-NOR GATE

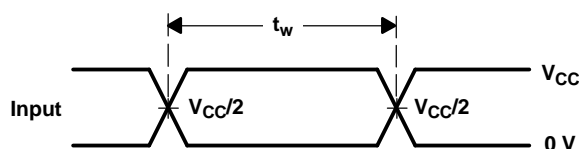
SCES511A–NOVEMBER 2003–REVISED MARCH 2005

### PARAMETER MEASUREMENT INFORMATION

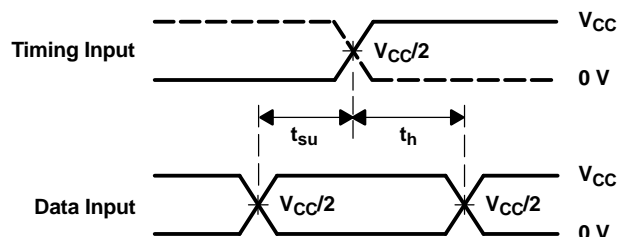


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

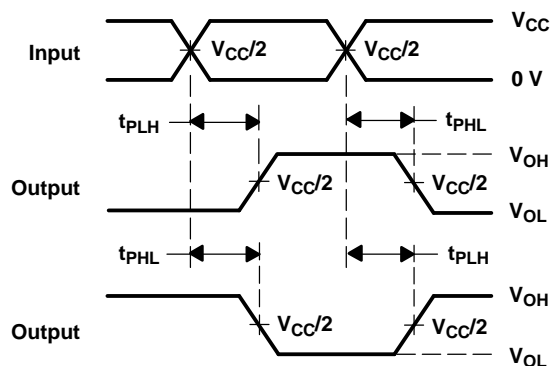
$V_{CC}$	$C_L$	$R_L$	$V_{\Delta}$
0.8 V	15 pF	2 k $\Omega$	0.1 V
1.2 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.8 V $\pm$ 0.15 V	15 pF	2 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	15 pF	2 k $\Omega$	0.15 V
1.8 V $\pm$ 0.15 V	30 pF	1 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	30 pF	500 $\Omega$	0.15 V



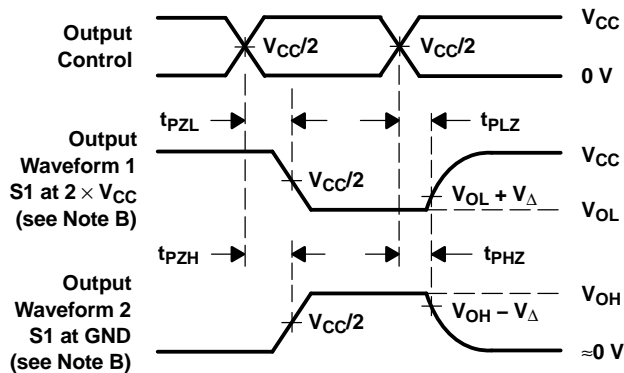
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ , slew rate  $\geq$  1 V/ns.
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AUC02RGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

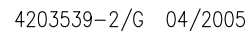
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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NOTES:

A.	All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B.	This drawing is subject to change without notice.
C.	QFN (Quad Flatpack No-Lead) package configuration.
<u>D.</u>	The package thermal pad must be soldered to the board for thermal and mechanical performance.
<u>E.</u>	Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
F.	Package complies to JEDEC MO-241 variation BA.

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